

Rigid PCB Roadmap

Item	Technology Routing			Remarks
	2015	2016	2017	
Layer	14	18	20	Scaling to 28 Layers by 2019
Max. Board Size	36in x 24in	41 in x 24in	43in x 26in	
Max. Board Thickness	315mil	315mil	394mil	
Min. Board Thickness	4mil	4mil	4mil	Can do 2mil with special request
Min. Core Thickness	2mil	2mil	1.5mil	Moving to 1mil in 2019
Max. Final Copper Thickness	Inner Layer	120Z	120Z	
	Outer Layer	120Z	120Z	
Min. Line Width/Space	4mil/4mil	4mil/4mil	3mil/3mil	Moving to 2.5mil/2.5mil in 2019
Min. CNC Drilling Size	10mil	8mil	8mil	R&D on 6mil
Min. Laser Drilling Size	4mil	4mil	4mil	R&D on 3mil
Min. Pad	Inner Layer	6.7mil	6mil	5.5mil
	Outer Layer	7mil	6.3mil	6mil
Min. Distance Between Via edge to Edge	11mil	10mil	9mil	
Min. Distance Between Via to Line	7mil	6.3mil	6mil	
Aspect Ratio	13:01	15:01	18:01	
Impedance Tolerance Control	±10%	±10%	±10%	Special request to TDR ±5%
HDI Ability	R&D	4+N+4	4+N+4	
Embedded Capacitance	Mass Production	Mass Production	Mass Production	